

Title (en)
ELECTRICALLY CONDUCTIVE POLYAMIDE SUBSTRATE

Title (de)
ELEKTRISCH LEITFÄHIGES POLYAMIDSUBSTRAT

Title (fr)
SUBSTRAT EN POLYAMIDE ÉLECTROCONDUCTEUR

Publication
EP 2841503 B1 20180829 (EN)

Application
EP 13719532 A 20130426

Priority
• EP 12165949 A 20120427
• EP 2013058749 W 20130426
• EP 13719532 A 20130426

Abstract (en)
[origin: WO2013160454A2] The invention relates to an electrically conductive system comprising a substrate and at least one conductive track adhered onto the substrate, wherein the substrate is composed of at least a polyamide and the conductive track is made out of an electrically conductive material and wherein the conductive track is adhered to the substrate by an jet printing technique followed by sintering. The invention further relates to a process for the production of an electrically conductive system and to its uses.

IPC 8 full level
C08L 77/00 (2006.01); **B32B 15/088** (2006.01); **C09D 11/00** (2014.01); **H01B 1/02** (2006.01); **H05K 3/12** (2006.01)

CPC (source: CN EP US)
B32B 15/088 (2013.01 - CN); **C08G 69/265** (2013.01 - EP US); **C08K 7/14** (2013.01 - EP US); **C08L 77/02** (2013.01 - EP US); **C08L 77/06** (2013.01 - CN EP US); **C09D 11/322** (2013.01 - EP US); **C09D 11/52** (2013.01 - CN EP US); **H01B 1/02** (2013.01 - CN EP US); **H01Q 1/38** (2013.01 - EP US); **H05K 1/0313** (2013.01 - US); **H05K 1/0346** (2013.01 - EP US); **H05K 1/0393** (2013.01 - EP US); **H05K 1/092** (2013.01 - US); **H05K 3/125** (2013.01 - CN US); **C08L 2201/02** (2013.01 - CN); **C08L 2203/20** (2013.01 - CN US); **C08L 2205/02** (2013.01 - CN); **C08L 2205/025** (2013.01 - US); **H05K 3/14** (2013.01 - EP US)

C-Set (source: CN EP US)

CN
1. **C08L 77/06 + C08K 7/14**
2. **C08L 77/06 + C08L 77/06 + C08K 7/14**
3. **C08L 77/06 + C08L 77/06**
4. **C08L 77/06 + C08K 7/14 + C08K 3/016**
EP US
1. **C08L 77/06 + C08K 7/14 + C08L 77/02**
2. **C08L 77/06 + C08K 7/14 + C08L 77/06**

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
WO 2013160454 A2 20131031; WO 2013160454 A3 20131219; CN 104254572 A 20141231; CN 104254572 B 20170405; EP 2841503 A2 20150304; EP 2841503 B1 20180829; IN 8365DEN2014 A 20150508; JP 2015520800 A 20150723; JP 6146723 B2 20170614; KR 102066304 B1 20200114; KR 20150004354 A 20150112; TW 201349968 A 20131201; TW I592079 B 20170711; US 2015107877 A1 20150423; US 2018371242 A1 20181227

DOCDB simple family (application)
EP 2013058749 W 20130426; CN 201380021791 A 20130426; EP 13719532 A 20130426; IN 8365DEN2014 A 20141008; JP 2015507555 A 20130426; KR 20147029925 A 20130426; TW 102115083 A 20130426; US 201314396652 A 20130426; US 201816118429 A 20180830